PIC32MZ EF FAMILY

PIC32MZ Embedded Connectivity with Floating Point Unit (EF) Family Silicon Errata and Data Sheet Clarification

The PIC32MZ Embedded Connectivity with Floating Point Unit (EF) family of devices that you have received conform functionally to the current Device Data Sheet (DS60001320), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in Table 1. The silicon issues are summarized in Table 2.

The errata described in this document will be addressed in future revisions of the PIC32MZ Embedded Connectivity with Floating Point Unit (EF) family silicon.

Note:	This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated in the last column of Table 2 apply to the current silicon revision (B3).

Data Sheet clarifications and corrections (if applicable) start on page 16, following the discussion of silicon issues.

The silicon revision level can be identified using the current version of MPLAB® X IDE and Microchip's programmers, debuggers and emulation tools, which are available at the Microchip corporate web site (www.microchip.com).

For example, to identify the silicon revision level using MPLAB X IDE in conjunction with a hardware debugger:

1. Using the appropriate interface, connect the device to the hardware debugger.
2. Open an MPLAB X IDE project.
3. Configure the MPLAB X IDE project for the appropriate device and hardware debugger.
4. Select *Window > Dashboard*, and then click the **Refresh Debug Tool Status** icon ( ).
5. The part number and the Device and Revision ID values appear in the **Output** window.

Note:	If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

The Device and Revision ID values for the various PIC32MZ EF Family silicon revisions are shown in Table 1.

TABLE 1: SILICON DEVREV VALUES

Part Number	Device ID(1)	Revision ID for Silicon Revision(1)			
		A1	A3	B2	B3
PIC32MZ0512EFE064	0x7201053	0x1	0x3	0x6	0x7
PIC32MZ0512EFF064	0x7206053				
PIC32MZ0512EFK064	0x722E053				
PIC32MZ1024EFE064	0x7202053				
PIC32MZ1024EFF064	0x7207053				
PIC32MZ1024EFK064	0x722F053				
PIC32MZ1024EFG064	0x7203053				
PIC32MZ1024EFH064	0x7208053				
PIC32MZ1024EFM064	0x7230053				
PIC32MZ2048EFG064	0x7204053				
PIC32MZ2048EFH064	0x7209053				
PIC32MZ2048EFM064	0x7231053				

Note 1: Refer to the **"Memory Organization"** and **"Special Features"** chapters in the current Device Data Sheet (DS60001320) for detailed information on Device and Revision IDs for your specific device.

TABLE 1: SILICON DEVREV VALUES (CONTINUED)

Part Number	Device ID(1)	Revision ID for Silicon Revision(1)			
		A1	A3	B2	B3
PIC32MZ0512EFE100	0x720B053	0x1	0x3	0x6	0x7
PIC32MZ0512EFF100	0x7210053				
PIC32MZ0512EFK100	0x7238053				
PIC32MZ1024EFE100	0x720C053				
PIC32MZ1024EFF100	0x7211053				
PIC32MZ1024EFK100	0x7239053				
PIC32MZ1024EFG100	0x720D053				
PIC32MZ1024EFH100	0x7212053				
PIC32MZ1024EFM100	0x723A053				
PIC32MZ2048EFG100	0x720E053				
PIC32MZ2048EFH100	0x7213053				
PIC32MZ2048EFM100	0x723B053				
PIC32MZ0512EFE124	0x7215053	0x1	0x3	0x6	0x7
PIC32MZ0512EFF124	0x721A053				
PIC32MZ0512EFK124	0x7242053				
PIC32MZ1024EFE124	0x7216053				
PIC32MZ1024EFF124	0x721B053				
PIC32MZ1024EFK124	0x7243053				
PIC32MZ1024EFG124	0x7217053				
PIC32MZ1024EFH124	0x721C053				
PIC32MZ1024EFM124	0x7244053				
PIC32MZ2048EFG124	0x7218053				
PIC32MZ2048EFH124	0x721D053				
PIC32MZ2048EFM124	0x7245053				
PIC32MZ0512EFE144	0x721F053	0x1	0x3	0x6	0x7
PIC32MZ0512EFF144	0x7224053				
PIC32MZ0512EFK144	0x724C053				
PIC32MZ1024EFE144	0x7220053				
PIC32MZ1024EFF144	0x7225053				
PIC32MZ1024EFK144	0x724D053				
PIC32MZ1024EFG144	0x7221053				
PIC32MZ1024EFH144	0x7226053				
PIC32MZ1024EFM144	0x724E053				
PIC32MZ2048EFG144	0x7222053				
PIC32MZ2048EFH144	0x7227053				
PIC32MZ2048EFM144	0x724F053				

Note 1: Refer to the **"Memory Organization"** and **"Special Features"** chapters in the current Device Data Sheet (DS60001320) for detailed information on Device and Revision IDs for your specific device.

TABLE 2: SILICON ISSUE SUMMARY

Module	Feature	Issue	Issue Summary	Affected Revisions(1)			
				A1	A3	B2	B3
Oscillator	Reference Clock	1.	The Reference Clock cannot divide input frequencies greater than 100 MHz.	X	X	X	X
Oscillator	Primary Oscillator Crystal	2.	**Revision A1 Silicon:** A crystal oscillator cannot be used as an input to the Primary Oscillator (OSC1/OSC2 pins). **Revision A3 and B3 Silicon:** The Primary Oscillator has been tested in a normal power-up sequence and supports specific crystal operation.	X	X	X	X
Oscillator	FRC Tuning	3.	The OSCTUN register only increases the frequency of the FRC.	X			
Secondary Oscillator	Crystal Use	4.	The Secondary Oscillator (SOSC) does not support crystal operation.	X	X		
Power-Saving	PMD bits	5.	Turning off REFCLK through the PMD bits causes unpredictable device behavior.	X	X		
I2C	—	6.	The I^2C module does not function reliably under certain conditions.	X	X		
UART	Auto-baud	7.	The Auto-baud feature does not function to set the baud rate.	X	X	X	X
UART	Synchronization	8.	On a RX FIFO overflow, shift registers stop receiving data, which causes the UART to lose synchronization.	X	X	X	X
USB	Suspend Mode	9.	The USB module will not function if the device enters Sleep mode and the USB PHY is turned off by setting the USBSSEN bit in the CFGCON register to '1'.	X	X	X	X
Power-Saving Modes	Sleep Mode	10.	The device may not exit Sleep mode.	X	X		
ADC	Digital Filters	11.	Using multiple digital filters may result in data not being captured accurately.	X	X		
ADC	Level Trigger	12.	The ADC level trigger will not perform burst conversions in Debug mode.	X	X		
ADC	DNL	13.	In Differential mode, DNL for code 3072 is out of specification.	X	X	X	X
ADC	Low-voltage Operation	14.	When the operating voltage (VDD/AVDD) is below 2.5V (i.e., charge pumps are ON), only one ADC core can be used.	X	X	X	X
ADC	Turbo Mode	15.	Turbo mode is not functional.	X	X	X	X
USB	Resume	16.	The USB module does not support remote wake-up.	X	X	X	X
Oscillator	External Clock Mode	17.	The EC mode timing specifications for the Primary Oscillator (POSC) are not met.	X			
Temperature Sensor	—	18.	The Temperature Sensor does not function.	X	X	X	X
ICSP	TDO	19.	The TDO pin becomes an output and toggles while programming on any ICSP™ PGECx/PGEDx pair.	X	X	X	X
DMA	PMD bits	20.	Setting the PMD bit for DMA (PMD7<4>) does not disable clocks or the DMA peripheral.	X	X	X	X

Note 1: Only those issues indicated in the last column apply to the current silicon revision.

TABLE 2: SILICON ISSUE SUMMARY (CONTINUED)

Module	Feature	Issue	Issue Summary	Affected Revisions(1)			
				A1	A3	B2	B3
PMP	Status Bits	21.	The PMP input buffer full flag, IB0F, and the output buffer underflow, OBUF, are set as soon as the PMP is turned on in Client mode (when TTLEN = 1).	X	X	X	X
Sleep	IPD	22.	A 3 mA increase occurs during Sleep mode when PB5DIV is disabled.	X	X	X	X
SQI	RX/TX FIFO	23.	The SQI may continuously receive invalid data or fail to transmit when the SQICLKDIV is used.	X	X	X	X
POR	GPIO	24.	Whenever VDD is less than1.75V, the I/O pin states may be indeterminate.	X	X		
Crypto	Partial Packet	25.	The cryptographic DMA module does not support partial packet processing.	X	X	X	X
Crypto	Zero Length Packet	26.	Zero length packets fail to process. The crypto DMA does not support an empty string hash.	X	X	X	X
SPI	Block Transmission	27.	At the end of a transmission, the SRMT bit can indicate the completion of the transmission for one PBCLK even though the transmission has one block remaining.	X	X	X	X
SQI	Special Function Registers	28.	The CPU stalls if the SQI Special Function Registers are read before the REFCLKO2 clock is enabled after a Reset.	X	X	X	X
Sleep	Wake-ups	29.	Multiple sleep attempts which occur before the CPU has fully awakened, may stall the CPU until the next reset event.	X	X	X	X
Security	System Bus Access	30.	The note at the end of the CFGPG register (Register no. 34-10) indicates that the CPU as system bus initiator is controlled within the CPU core is incorrect. The CPU core internal state will not control the CPU system bus initiator permission group.	X	X		
UART	High Speed Mode	31.	The UART Stop bit duration is shorter than expected in High-Speed mode (UxMODE.BRGH =1) for baud rates less than 7.5 Mbps.	X	X	X	X
Reset	NMI Number	32.	The NMICNT bit field in the RNMICON register is 8 bits instead of 16 bits.	X	X		
I2C3	I2C3	33.	I^2C3 on the A3 revision is non functional.		X		
USB	Host Disconnect Detection	34.	The USB Host module does not wake up CPU from sleep when a USB device is disconnected.	X	X	X	X
USB	LPM	35.	The USB Link Power Management (LPM) feature is not functional.	X	X	X	X
USB	Host Resume	36.	The USB Host module does not send correct resume signal on the USB bus on subsequent suspend/resume sequences.	X	X	X	X
I2C	Speed	37.	The I^2C module does not meet low period of the SCL clock (tLOW) parameter from I^2C specification for clock frequency >= 400 kHz.	X	X	X	X

Note 1: Only those issues indicated in the last column apply to the current silicon revision.

TABLE 2: SILICON ISSUE SUMMARY (CONTINUED)

Module	Feature	Issue	Issue Summary	Affected Revisions(1)			
				A1	A3	B2	B3
System Bus	Speed	38.	When SYSCLK >184 MHz and Flash Wait states = 2, device operation does not conform to published PROGRAM FLASH MEMORY WAIT STATES specification.			X	X
ADC	External VREF	39.	Excessive current flows through the VREF- pin when external voltage reference is used, and voltage on the VREF- pin is greater than AVss.	X	X	X	X
USB	FIFO	40.	Writing '1' to the FLUSH bit (USBIENCSRx<19>, where x =1-7) does not flush the TX FIFO and reset the TX FIFO pointer.	X	X	X	X
EBI	FBIRDYx pin as GPIO	41.	EBIRDYEN1 bit (CFGEBIC<25>), EBIRDYEN2 bit (CFGEBIC<26>), EBIRDYEN3 bit (CFGEBIC<27>) are not functional and always set to '1'.	X		X	X
DMA	Channel Destination Half Full Interrupt	42.	DMA Channel Destination Half Full interrupt can trigger twice.	X	X	X	X
Device	Peripheral Bus x Clock Divisor Control	43.	Cannot wake-up from sleep by pin change interrupt.	X	X	X	X
Timer2-9	Match	44.	If timer match coincides with entry into sleep mode, timer event triggers and interrupt may not occur.	X	X	X	X
Flash - RTSP	RTSP	45.	Run-Time Self Programming of Configuration Words is not functional.	X	X	X	X

Note 1: Only those issues indicated in the last column apply to the current silicon revision.

Silicon Errata Issues

Note:	This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the shaded column in the following tables apply to the current silicon revision (**B3**).

1. Module: Oscillator

The Reference Module cannot divide input frequencies greater than 100 MHz. Therefore, SYSCLK cannot be divided if the SYSCLK operates at frequencies greater than 100 MHz.

Work around

Instead of using SYSCLK, use PBCLK1 as the input, which is limited to 100 MHz and is synchronized to SYSCLK.

Alternatively, do not divide the SYSCLK and allow the destination peripheral (i.e., SQI, SPI) to divide it as needed. To do this, set the RODIV<14:0> bits and the ROTRIM<8:0> bits to '0'.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

2. Module: Oscillator

Revision A1 Silicon: A crystal oscillator cannot be used as an input to the Primary Oscillator (POSC) pins OSC1 and OSC2.

Silicon Work around

Use an external clock or the Internal FRC Oscillator.

Revision A3 and B3 Silicon: The POSC has been tested in a normal power-up sequence and supports specific crystal operation.

Silicon Work around 1

The Primary Oscillator (POSC) has been characterized to operate at 8 MHz, 12 MHz, and 24 MHz when the circuit in Figure 1 is implemented, and the operating conditions listed in Table 3 are met.

FIGURE 1: POSC CRYSTAL CIRCUIT

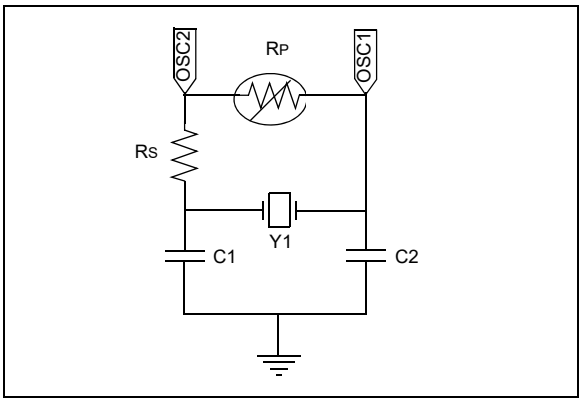


TABLE 3: CRYSTAL SPECIFICATIONS

Crystal Frequency (see Note 1)	Series Resistor (Rs)	POSC Gain Setting POSCGAIN<1:0> (DEVCFG0<20:19>)	POSC Boost Setting POSCBOOST (DEVCFG0<21>)
8 MHz	2 kΩ	'0b00 (GAIN_0)	'0b1 (ON)
12 MHz	1 kΩ	'0b00 (GAIN_0)	'0b1 (ON)
24 MHz	0 kΩ	'0b00 (GAIN_0))	'0b1 (ON)

Note 1: Using any other crystal frequency will require special component selection and characterization.

2: A parallel resistor (RP) should not be used to increase the gain of the POSC.

Silicon Work around 2

Alternatively, use an external clock or the Internal FRC oscillator.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

3. Module: Oscillator

The OSCTUN register only increases the frequency of the FRC, which results in the TUN<5:0> bits (OSCTUN<5:0>) functioning as follows:

TUN<5:0>: FRC Oscillator Tuning bits

111111 = Center frequency +4%

111110 =

.
.
.

000001 =

000000 = Center frequency; Oscillator runs at nominal frequency (8 MHz)

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X							

4. Module: Secondary Oscillator

A crystal oscillator cannot be used as the input to the Secondary Oscillator (SOSC) pins SOSCI and SOSCO.

Silicon Work around

Use an external clock source (32,768 Hz) applied to the SOSCO pin with the FSOSCEN bit (DEVCFG1<6>) set to '0' (i.e., the SOSC is disabled through the Configuration Word) for a real-time clock base; otherwise, use the internal LPRC for non-precision requirements.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

5. Module: Power-Saving

Turning off the REFCLK modules through the PMD bits causes unpredictable behavior.

Work around

None. Do not disable the REFCLK modules through the PMD bits.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

6. Module: I²C

Indeterminate I²C module behavior may result when data rates > 100 kHz and/or continuous sequential data transfers > 500 bytes are used.

The potential false intermittent error signals can result in one of the following error conditions, which are listed in order of decreasing frequency:

- **False Error Condition 1:**
  False Host Bus Collision Detect (Host-mode only) – The error is indicated through the BCL bit (I2CxSTAT<10>).
- **False Error Condition 2:**
  Receive Overflow (Host or Client modes) – The error is indicated through the I2COV bit (I2CxSTAT<20>).
- **False Error Condition 3:**
  Suspended I²C Module Operations (Host or Client modes) – I²C transactions in progress are inadvertently suspended without error indications.

Note:	All three false error conditions are recoverable in software.

Revision A1 Silicon Work around 1

False Error Condition 1:

Clear the Host Bus Collision Detect (BCL bit (I2CxSTAT<10>), after the bus returns to an Idle state. The software can monitor the S bit (I2CxSTAT<3>) and the P bit (I2CxSTAT<4>) to wait for an Idle bus. When the software services the bus collision Interrupt Service Routine and the I²C bus is free, the software can resume communication by asserting a new Start condition.

False Error Condition 2:

Clear the Receive Overflow Status flag I2COV bit (I2CxSTAT<20>), and then resume normal operation.

False Error Condition 3:

First, initialize a Timer to slightly greater than the worst case I²C transaction cycle, (i.e., from Start-to-Stop, including the sum of all other application PC flow latencies, calls, interrupts, etc.). Exact timing is not required, rather just long enough so that a normal transaction is not interrupted. Prior to the beginning of each transaction, start the timer. Be sure to stop and reset the timer after completion of each successful I²C transaction.

Then, during the Timer interrupt (meaning the I²C transaction has timed out), disable the I²C module by setting the ON bit (I2CxCON<15>) = `0`. After disabling the module, wait 4 instruction cycles, after which time the I2CxSTAT register will automatically be cleared. Then, re-enable the I²C module by setting the ON bit = `1` and resume normal operation.

Revision A1 Silicon Work around 2

Instead of using the hardware I²C module, use a software “bit-bang” implementation.

Revision A3 Silicon Work around

The work arounds described for revision A1 silicon will also work for silicon revision A3, with the exception of I2C3, as I2C3 must use a software “bit-bang” implementation.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

7. Module: UART

The UART automatic baud rate feature is intended to set the baud rate during run-time based on external data input. However, this feature does not function.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

8. Module: UART

During a RX FIFO overflow condition, the shift register stops receiving data. This causes the UART to lose synchronization with the serial data stream. The only way to recover from this is to turn the UART OFF and ON until it synchronizes. This could require several OFF/ON sequences.

Work arounds

Work around 1:

Avoid the RX overrun condition by ensuring that the UARTx module has a high enough interrupt priority such that other peripheral interrupt processing latencies do not exceed the time to overrun the UART RX buffer based on the application baud rate. Alternately or in addition to, set the URXISEL bits in the UxSTA register to generate an earlier RX interrupt based on RX FIFO fill status to buy more time for interrupt latency processing requirements.

Work around 2:

If avoiding RX FIFO overruns is not possible, implement an ACK/NAK software handshake protocol to repeat lost packet transfers after restoring the UART synchronization.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

9. Module: USB

The USB module will not function if the device enters Sleep mode and the USB PHY is turned off by setting the USBSSEN bit in the CFGCON register to '1'.

Work around

Keep the USB PHY operational in Sleep mode by setting the USBSSEN bit to '0'.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

10. Module: Power-Saving Modes

The device may not exit Sleep mode when Flash is powered down through the FSLEEP bit in the DEVCFG0/ADEVCFG0 Configuration register.

Work around

Enable Flash in Sleep mode by clearing the Flash Sleep Mode Configuration bit, FSLEEP, in the DEVCFG0/ADEVCFG0 Configuration register.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

11. Module: ADC

When using multiple digital filters, the filters may not capture data correctly when the assigned data sources are ready at the same time.

Work around

Only one digital filter may be used at a time.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

12. Module: ADC

The ADC level trigger will not perform burst conversions in Debug mode.

Work around

Do not use Debug mode with the ADC level trigger.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

13. Module: ADC

In Differential mode, code 3072 has a DNL of +3.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

14. Module: ADC

When the operating voltage (VDD/AVDD) is below 2.5V (i.e., charge pumps are ON), only one ADC core can be used.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

15. Module: ADC

Turbo mode is not functional when two channels are linked for the purpose of increasing throughput.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

16. Module: USB

The USB module does not support remote wakeup through the USBRIE bit (USBCRCON<1>).

Work around

None.

USB descriptors must inform the host that the device does not support remote wake-up.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

17. Module: Oscillator

The Primary Oscillator in EC mode only functions up to 24 MHz

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X							

18. Module: Temperature Sensor

The temperature sensor does not function.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

19. Module: ICSP

Regardless of other functions shared on the TDO pin, the TDO function becomes an active output and toggles while programming on any ICSP PGECx/PGEDx pair.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

20. Module: DMA

Setting the PMD bit for DMA (PMD7<4>) does not disable clocks or the DMA peripheral.

Work around

None.

A1	A3	B2	B3				
X	X	X	X				

21. Module: PMP

The PMP input buffer full flag, IB0F, and the output buffer underflow, OBUF, are set as soon as the PMP is turned on in Client mode (when TTLEN = 1).

Work around

After PMP initial initialization is complete, and before the PMP and interrupts are enabled, clear the TTLEN bits in user software.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

22. Module: Sleep

If the ON bit (PB5DIV<15>) = 0 and PBCLK5 is disabled, a 3 mA increase in Sleep IPD current occurs.

Work around

Do not disable PBCLK5 before entering Sleep mode.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

23. Module: SQI

When the SQI clock divider is used (by setting CLKDIV ≠ 0), any one of the following error conditions may occur on some of the devices, which are depending on the DDRMODE setting:

- With DDRMODE = 0, the SQI fails in reception only.
- With DDRMODE = 1, the SQI may fail in both reception and transmission.

Work around

Set the CLKDIV bits to '0' and use the REFCLK02 as the SQI base clock.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

24. Module: POR

Whenever V_{DD} is less than 1.75V, the I/O pin state and logic level may be indeterminate.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

25. Module: Crypto

Attempting to run part of a cryptographic packet through the peripheral may not result in a usable initial vector for continuing the cryptographic operation.

Work around

Do not interrupt a cryptographic operation with another, instead, always process a hash completely.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

26. Module: Crypto

Using the crypto DMA on an empty hash string will cause the peripheral to time out and not return a valid hash.

Work around

Use the fixed known hash of the empty string.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

27. Module: SPI

Just before the last block of a transmission is shifted out to the SPI pins, the SRMT bit may incorrectly indicate that the transmission is done. However, this does not affect the Transmit Buffer Empty Interrupt (STXISEL = 0).

Work around

Use the interrupt notification rather than polling the SRMT bit to determine when a transmission has completed.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

28. Module: SQI

Read access to SQI SFRs stalls the CPU when REFCLKO2 is disabled.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

29. Module: Sleep

Multiple sleep attempts (WAIT instruction with OSCCON<4>=1) which occur within 20 µs of a wake event, before the CPU has fully awakened, can cause the CPU to stall until a Power-on Reset (POR) event.

Work around

Ensure that at least 20 µs elapse before attempting to put the CPU to sleep (WAIT instruction with OSCCON<4>=1) after it awakens from a previous sleep.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

30. Module: Security

The note at the end of the CFGPG register (Register no. 34-10) indicates that the CPU as a system bus initiator is controlled within the CPU core is incorrect. The CPU core internal state will not control the CPU system bus initiator permission group.

Work around

Use the CFGPG register reserved bits <1:0> to control the permission group ID of the CPU as a system bus initiator.

11 = Initiator is assigned to permission group 3

10 = Initiator is assigned to permission group 2

01 = Initiator is assigned to permission group 1

00 = Initiator is assigned to permission group 0

Also, the reserved bits <:14:12> of the DEVCFG0 and ADEVCFG0 registers can be used to control the permission group ID of the CPU in Debug mode, as in:

- 1xx = Allow CPU access to permission group 2 permission regions
- x1x = Allow CPU access to permission group 1 permission regions
- xx1 = Allow CPU access to permission group 0 permission regions
- 0xx = Deny CPU access to permission group 2 permission regions
- x0x = Deny CPU access to permission group 1 permission regions
- xx0 = Deny CPU access to permission group 0 permission regions

When the CPU is in Debug mode and CFGPG<1:0> are set to a denied permission group as defined by the DEVCFG0<14:12>, the transaction request is assigned Group 3 permissions.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

31. Module: UART

The UART TX Stop bit duration is shorter than the expected in High-Speed mode (BRGH (UxMODE<3>) = 1) for baud rates less than 7.5 Mbps.

Work around

For baud rates less than 7.5 Mbps, operate the UART in Standard-Speed mode, that is, BRGH (UxMODE<3>) =0. For baud rates greater than 7.5 Mbps operate the UART in High-Speed mode, that is, BRGH (UxMODE<3>) =1.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

32. Module: Reset

The NMICNT bit field in the RNMICON register is 8 bits instead of 16 bits. It has limited to values 0 through 255.

Work around

The user must update the NMICNT register immediately upon entry into NMI ISR in their code with an 8-bit value not to exceed 0xFF. If the user needs to extend the NMI reset event >257 clock counts, the NMICNT register can be updated many times as required inside the NMI to ensure users NMI routine can complete before the pending reset.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X						

33. Module: I2C3

I2C3 on the A3 revision is non functional.

Work around

Silicon revision A3 I2C3 must use a software “bit-bang” implementation.

Affected Silicon Revisions

A1	A3	B2	B3				
	X						

34. Module: USB

The USB Host module does not wake up CPU from sleep when a USB device is disconnected.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

35. Module: USB

The USB Link Power Management (LPM) feature is not functional.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

36. Module: USB

The USB Host module will send a correct resume signal on the first suspend or sleep sequence, but not on subsequent suspend or sleep sequences.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

37. Module: I^2C

The I^2C host module does not meet low period of the SCL clock (tLOW) parameter from I^2C specification for clock frequency >= 400 kHz.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

38. Module: System Bus

Device operation does not conform to published PROGRAM FLASH MEMORY WAIT STATES specification of the following:

Required Flash Wait States	SYSCLK	Units
With ECC: 2 Wait states	120 < SYSCLK ≤ 200	MHz
Without ECC: 2 Wait states	140 < SYSCLK ≤ 200	MHz

This may result in undetermined device operation.

Work around

Configure the device to the following specification:

Required Flash Wait States	SYSCLK	Units
With ECC:		MHz
2 Wait states	120 < SYSCLK ≤ 184	
3 Wait states	184 < SYSCLK ≤ 200	
Without ECC:		MHz
2 Wait states	140 < SYSCLK ≤ 184	
3 Wait states	184 < SYSCLK ≤ 200	

Increasing Flash wait states in the user application from 2 to 3 will impact the CPU performance by <2% if the cache is enabled.

Affected Silicon Revisions

A1	A3	B2	B3				
		X	X				

39. Module: ADC

Excessive current flows through the VREF- pin when the external voltage reference is used, and the voltage on the VREF- pin is greater than AVss.

Work around

Connect the VREF- pin to AVss. Input dynamic range can be changed after varying voltage on the VREF+ pin.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

40. Module: USB

Writing '1' to the FLUSH bit (USBIENCSRx <19>, where x = 1-7) does not flush the TX FIFO and reset the TX FIFO pointer. As a result, the TXPKTRDY bit (USBIENCSRx <16>, where x =1-7) is not cleared and the USB interrupt is not generated.

Work around

To clear the TX FIFO, simultaneously set the FLUSH bit (USBIENCSRx <19>, where x = 1-7) and clear the TXPKTRDY bit (USBIENCSRx <16>, where x = 1-7). This sequence must be repeated twice to flush the FIFO.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

41. Module: EBI

The EBIRDYEN1 bit (CFGEBIC <25>), EBIRDYEN2 bit (CFGEBIC <26>), EBIRDYEN3 bit (CFGEBIC <27>) are not functional and always set to '1'.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X		X	X				

42. Module: DMA

If the DMA Channel Destination Half Full Interrupt Enable bit is set (DCHxINT.CHDIE = 1), the Channel Destination Half Full Interrupt Flag (DCHxINT.CHDHIF) bit can trigger twice. When the DCHxINT.CHDHIF bit triggers at n/2 byte and is cleared immediately by software, the DCHxINT.CHDHIF bit can trigger at ((n/2) + 1) byte also.

Work around

Clear the DCHxINT.CHDHIF bit along with the Channel Block Transfer Complete Interrupt Flag (DCHxINT.CHBCIF) bit.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

43. Module: Device

When the Peripheral Bus x Clock Divisor Control bits (PBxDIV.PBDIV) are greater or equal to three and the device is set in Sleep mode, the device cannot be woken up by a pin change interrupt.

Work around

Change the PBxDIV.PBDIV bits to equal or less than two before entering Sleep mode, then return PBxDIV.PBDIV to the required value after waking up from Sleep mode.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

44. Module: Timer2-9

If timer match coincides with entry into Sleep mode, timer event triggers and interrupt may not occur.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

45. Module: Flash - RTSP

Run-Time Self Programming of Configuration Words is not functional.

Work around

None.

Affected Silicon Revisions

A1	A3	B2	B3				
X	X	X	X				

Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS60001320H):

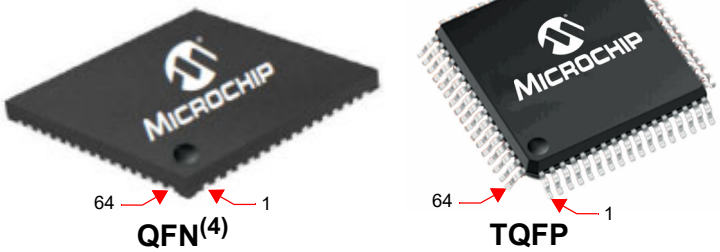
Note: Corrections in tables are shown in **bold**. Where possible, the original bold text formatting has been removed for clarity.

1. Module: Ethernet

In Table 2. "*Pin Names for 64-pin QFN and TQFP Devices*" of the current data sheet, the AECRSDV signal was erroneously omitted from the pin number 44 and added to the pin number 62. The correct assignment is shown in bold type in the following table.

64-PIN QFN(4) AND TQFP (TOP VIEW)

PIC32MZ0512EF(E/F/K)064
PIC32MZ1024EF(G/H/M)064
PIC32MZ1024EF(E/F/K)064
PIC32MZ2048EF(G/H/M)064

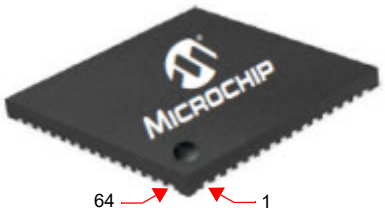


Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN17/ETXEN/RPE5/PMD5/RE5	33	VBUS
2	AN16/ETXD0/PMD6/RE6	34	VUSB3V3
3	AN15/ETXD1/PMD7/RE7	35	VSS
4	AN14/C1IND/RPG6/SCK2/PMA5/RG6	36	D-
5	AN13/C1INC/RPG7/SDA4/PMA4/RG7	37	D+
6	AN12/C2IND/RPG8/SCL4/PMA3/RG8	38	RPF3/USBID/RF3
7	VSS	39	VDD
8	VDD	40	VSS
9	MCLR	41	RPF4/SDA5/PMA9/RF4
10	AN11/C2INC/RPG9/PMA2/RG9	42	RPF5/SCL5/PMA8/RF5
11	AN45/C1INA/RPB5/RB5	43	AERXD0/ETXD2/RPD9/SDA1/PMCS2/PMA15/RD9
12	AN4/C1INB/RB4	44	**AECRSDV/ECOL/RPD10/SCL1/SCK4/RD10**
13	AN3/C2INA/RPB3/RB3	45	AERXCLK/AEREFCLK/ECRS/RPD11/PMCS1/PMA14/RD11
14	AN2/C2INB/RPB2/RB2	46	AERXD1/ETXD3/RPD0/RTCC/INT0/RD0
15	PGEC1/VREF-/CVREF-/AN1/RPB1/RB1	47	SOSCI/RPC13/RC13
16	PGED1/VREF+/CVREF+/AN0/RPB0/PMA6/RB0	48	SOSCO/RPC14/T1CK/RC14
17	PGEC2/AN46/RPB6/RB6	49	EMDIO/AEMDIO/RPD1/SCK1/RD1
18	PGED2/AN47/RPB7/RB7	50	ETXERR/AETXEN/RPD2/SDA3/RD2
19	AVDD	51	AERXERR/ETXCLK/RPD3/SCL3/RD3
20	AVss	52	SQICS0/RPD4/PMWR/RD4
21	AN48/RPB8/PMA10/RB8	53	SQICS1/RPD5/PMRD/RD5
22	AN49/RPB9/PMA7/RB9	54	VDD
23	TMS/CVREFOUT/AN5/RPB10/PMA13/RB10	55	VSS
24	TDO/AN6/PMA12/RB11	56	ERXD3/AETXD1/RPF0/RF0
25	VSS	57	TRCLK/SQICLK/ERXD2/AETXD0/RPF1/RF1
26	VDD	58	TRD0/SQID0/ERXD1/PMD0/RE0
27	TCK/AN7/PMA11/RB12	59	VSS
28	TDI/AN8/RB13	60	VDD

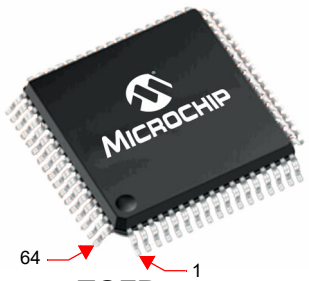
Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.4 "Peripheral Pin Select (PPS)"** for restrictions.
2: Every I/O port pin (RBx-RGx) can be used as a change notification pin (CNBx-CNGx). See **Section 12.0 "I/O Ports"** for more information.
3: Shaded pins are 5V tolerant.
4: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

64-PIN QFN(4) AND TQFP (TOP VIEW)

PIC32MZ0512EF(E/F/K)064
PIC32MZ1024EF(G/H/M)064
PIC32MZ1024EF(E/F/K)064
PIC32MZ2048EF(G/H/M)064



QFN(4)



TQFP

Pin #	Full Pin Name
29	AN9/RPB14/SCK3/PMA1/RB14
30	AN10/EMDC/AEMDC/RPB15/OCFB/PMA0/RB15
31	OSC1/CLKI/RC12
32	OSC2/CLKO/RC15

Pin #	Full Pin Name
61	TRD1/SQID1/ERXD0/PMD1/RE1
62	**TRD2/SQID2/ERXDV/ECRSDV/PMD2/RE2**
63	TRD3/SQID3/ERXCLK/EREFCLK/RPE3/PMD3/RE3
64	AN18/ERXERR/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.4 "Peripheral Pin Select (PPS)"** for restrictions.
2: Every I/O port pin (RBx-RGx) can be used as a change notification pin (CNBx-CNGx). See **Section 12.0 "I/O Ports"** for more information.
3: Shaded pins are 5V tolerant.
4: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

2. Module: Ethernet

In 64-pin QFN/TQFP column of Table 1-19. “Alternate Ethernet RMII Pinout I/O Descriptions” of the current data sheet, the AECRSDV signal was erroneously assigned to the pin number 62 instead of the pin number 44. The correct assignment is shown in bold type in the following table.

Pin Name	Pin Number						Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	100-pin TFBGA	124-pin VTLA	144-pin TQFP/ LQFP	144-pin TFBGA			
AERXD0	43	18	A3	—	—	—	I	ST	Alternate Ethernet Receive Data 0
AERXD1	46	19	A4	—	—	—	I	ST	Alternate Ethernet Receive Data 1
AERXERR	51	1	A9	—	—	—	I	ST	Alternate Ethernet Receive Error Input
AETXD0	57	47	J2	—	—	—	O	—	Alternate Ethernet Transmit Data 0
AETXD1	56	48	J1	—	—	—	O	—	Alternate Ethernet Transmit Data 1
AEMDC	30	70	K8	—	—	—	O	—	Alternate Ethernet Management Data Clock
AEMDIO	49	71	J8	—	—	—	I/O	—	Alternate Ethernet Management Data
AETXEN	50	67	J6	—	—	—	O	—	Alternate Ethernet Transmit Enable
AEREFCLK	45	16	D4	—	—	—	I	ST	Alternate Ethernet Reference Clock
AECRSDV	**44**	12	C5	—	—	—	I	ST	Alternate Ethernet Carrier Sense Data Valid

Legend: CMOS = CMOS-compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = Transistor-transistor Logic input buffer; PPS = Peripheral Pin Select

3. Module: EBI

The minimum values from Table 37-47. "EBI Timing Requirements" in the current product Data Sheet was erroneous. The correct values are listed in the table below:

TABLE 3-1: EBI TIMING REQUIREMENTS(1)

AC CHARACTERISTICS			Standard Operating Conditions: 2.1V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
EB10	TEBICLK	Internal EBI Clock Period (PBCLK8)	**10**	—	—	ns	—
EB11	TEBIRC	EBI Read Cycle Time (TRC<5:0>)	**30**	—	—	ns	—
EB12	TEBIPRC	EBI Page Read Cycle Time (TPRC<3:0>)	**30**	—	—	ns	—
EB13	TEBIAS	EBI Write Address Setup (TAS<1:0>)	**15**	—	—	ns	—
EB14	TEBIWP	EBI Write Pulse Width (TWP<5:0>)	**25**	—	—	ns	—
EB15	TEBIWR	EBI Write Recovery Time (TWR<1:0>)	**15**	—	—	ns	—
EB16	TEBICO	EBI Output Control Signal Delay	**—**	—	5	ns	See **Note 2**
EB17	TEBIDO	EBI Output Data Signal Delay	**—**	—	5	ns	See **Note 2**
EB18	TEBIDS	EBI Input Data Setup	**10**	—	—	ns	See **Note 2**
EB19	TEBIDH	EBI Input Data Hold	**3**	—	—	ns	See **Note 2, 3**

Note 1: EBI Timings Requirements data are from simulation.

2: Maximum pin capacitance = 10 pF.

3: Hold time from EBI Address change is 0 ns.

4. Module: IVREF DC Characteristics

The DC characteristics of IVREF, as shown in Table 37-14, have been updated (shown in **bold**):

TABLE 3-2: DC CHARACTERISTICS

Param. No.	Symbol	Characteristics	Minimum	Typical	Maximum	Units	Comments
D305	IVREF	Internal Voltage Reference	**1.182**	**1.214**	**1.245**	V	-

APPENDIX A: REVISION HISTORY

Rev A Document (7/2015)

Initial release of this document issued for revision A1 silicon, which includes silicon issues 1. Module: (Oscillator), 2. Module: (Oscillator), 3. Module: (Oscillator), 4. Module: (Secondary Oscillator), 5. Module: (Power-Saving), 6. Module: (I2C), 7. Module: (UART), 8. Module: (UART), 9. Module: (USB), and Power-Saving Modes.

Rev B Document (4/2016)

Added silicon issues 11. Module: (ADC) and 12. Module: (ADC).

Updated silicon issues 2. Module: (Oscillator) and 10. Module: (Power-Saving Modes).

Rev C Document (7/2016)

Updated to include silicon revision A3.

Updated silicon issues 2. Module: (Oscillator), 6. Module: (I2C), and 11. Module: (ADC).

Added silicon issues 13. Module: (ADC), 14. Module: (ADC), 15. Module: (ADC), and 16. Module: (USB).

Added data sheet clarifications 1. Module: (Resets) and 2. Module: (Interrupt Controller).

Rev D Document (9/2016)

Updated Figure 1 and Table 3 in silicon issue 2. Module: (Oscillator).

Added silicon issues 17. Module: (Oscillator) and 18. Module: (Temperature Sensor).

Added data sheet clarification 3. Module: (External Clock Timing Requirements).

Rev E Document (3/2018)

Internal release, minor content edits gone into this release.

Rev F Document (4/2018)

Added silicon issues: 19. Module: (ICSP), 20. Module: (DMA), 21. Module: (PMP), 22. Module: (Sleep), 23. Module: (SQI), 24. Module: (POR), 25. Module: (Crypto), 26. Module: (Crypto), 27. Module: (SPI), 28. Module: (SQI), and 29. Module: (Sleep).

All data sheet clarifications were removed.

Rev G Document (6/2018)

Updated to include silicon revision B2.

Added silicon issue 30. Module:Security.

Rev H Document (9/2018)

Added Silicon issues: 31. Module:UART.

Rev J Document (2/2019)

Added Silicon Issue 32. Module:Reset.

Added Data Sheet Clarifications: 1. Module:Ethernet, Appendix A:Revision History, and 33. Module:I2C3.

Updated Silicon Issue 2. Module:Oscillator.

Rev K Document (01/2020)

Added Silicon Issues 34. Module:USB, 35. Module:USB, 36. Module:USB, and 37. Module:I2C

Updated Silicon issue 28. Module:SQI.

All data sheet clarifications were removed.

Rev. L Document (06/2020)

Added silicon Issue 38. Module:System Bus.

Updated silicon issue 24. Module:POR.

Rev. M Document (09/2020)

Added Data Sheet Clarifications 1. Module:Ethernet, and 2. Module:Ethernet.

Updated TABLE 2:Silicon Issue Summary for issue 1 to include revision B2 silicon

Rev. N Document (05/2021)

Terminology for “Master” and “Slave” was updated to “Host” and “Client” respectively. This change may not be reflected in all associated Microchip documentation. For more information, contact a Microchip sales representative.

Added a new Data Sheet Clarification for 3. Module:EBI.

Added the following new silicon issues:

- 39. Module: (ADC)
- 40. Module: (USB)
- 41. Module: (EBI)
- 42. Module: (DMA)
- 43. Module: (Device)
- 44. Module: (Timer2-9)

Rev. P Document (03/2022)

The following Data Sheet clarifications were added:

- 4. Module:IVREF DC Characteristics

Rev. Q Document (07/2022)

The following errata were added in this revision:

- 45. Module: (Flash - RTSP)

Rev. R Document (04/2023)

The following updates were performed for this revision:

- Updated the Silicon revision to B3 throughout the document

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